Microchip Technology - PIC32MX150F128BT-50I/SS Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	21
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx150f128bt-50i-ss

TABLE 10: PIN NAMES FOR 44-PIN USB DEVICES

44-PIN QFN (TOP VIEW)(1,2,3,5)

PIC32MX210F016D
PIC32MX220F032D
PIC32MX230F064D
PIC32MX230F256D
PIC32MX250F128D
PIC32MX270F256D

44 1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	RPB9/SDA1/CTED4/PMD3/RB9	23	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/PMD2/RB2
2	RPC6/PMA1/RC6	24	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/PMWR/RB3
3	RPC7/PMA0/RC7	25	AN6/RPC0/RC0
4	RPC8/PMA5/RC8	26	AN7/RPC1/RC1
5	RPC9/CTED7/PMA6/RC9	27	AN8/RPC2/PMA2/RC2
6	VSS	28	VDD
7	VCAP	29	VSS
8	PGED2/RPB10/D+/CTED11/RB10	30	OSC1/CLKI/RPA2/RA2
9	PGEC2/RPB11/D-/RB11	31	OSC2/CLKO/RPA3/RA3
10	VUSB3V3	32	TDO/RPA8/PMA8/RA8
11	AN11/RPB13/CTPLS/PMRD/RB13	33	SOSCI/RPB4/RB4
12	PGED4/TMS/PMA10/RA10	34	SOSCO/RPA4/T1CK/CTED9/RA4
13	PGEC4/TCK/CTED8/PMA7/RA7	35	TDI/RPA9/PMA9/RA9
14	CVREFOUT/AN10/C3INB/RPB14/VBUSON/SCK1/CTED5/RB14	36	AN12/RPC3/RC3
15	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15	37	RPC4/PMA4/RC4
16	AVSS	38	RPC5/PMA3/RC5
17	AVDD	39	VSS
18	$\overline{\text{MCLR}}$	40	VDD
19	PGED3/VREF+/CVREF+/AN0/C3INC/RPA0/CTED1/PMD7/RA0	41	RPB5/USBID/RB5
20	PGEC3/VREF-/CVREF-/AN1/RPA1/CTED2/PMD6/RA1	42	VBUS
21	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/PMD0/RB0	43	RPB7/CTED3/PMD5/INT0/RB7
22	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/PMD1/RB1	44	RPB8/SCL1/CTED10/PMD4/RB8

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: This pin function is not available on PIC32MX110F016D and PIC32MX120F032D devices.

5: Shaded pins are 5V tolerant.

TABLE 1-1: PINOUT I/O DESCRIPTIONS

Pin Name	Pin Number(1)				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
AN0	27	2	33	19	I	Analog	Analog input channels.
AN1	28	3	34	20	I	Analog	
AN2	1	4	35	21	I	Analog	
AN3	2	5	36	22	I	Analog	
AN4	3	6	1	23	I	Analog	
AN5	4	7	2	24	I	Analog	
AN6	—	—	3	25	I	Analog	
AN7	—	—	4	26	I	Analog	
AN8	—	—	—	27	I	Analog	
AN9	23	26	29	15	I	Analog	
AN10	22	25	28	14	I	Analog	
AN11	21	24	27	11	I	Analog	
AN12	20(2)	23(2)	26(2) 11(3)	10(2) 36(3)	I	Analog	
CLKI	6	9	7	30	I	ST/CMOS	External clock source input. Always associated with OSC1 pin function.
CLKO	7	10	8	31	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with OSC2 pin function.
OSC1	6	9	7	30	I	ST/CMOS	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise.
OSC2	7	10	8	31	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
SOSCI	8	11	9	33	I	ST/CMOS	32.768 kHz low-power oscillator crystal input; CMOS otherwise.
SOSCO	9	12	10	34	O	—	32.768 kHz low-power oscillator crystal output.
REFCLKI	PPS	PPS	PPS	PPS	I	ST	Reference Input Clock
REFCLKO	PPS	PPS	PPS	PPS	O	—	Reference Output Clock
IC1	PPS	PPS	PPS	PPS	I	ST	Capture Inputs 1-5
IC2	PPS	PPS	PPS	PPS	I	ST	
IC3	PPS	PPS	PPS	PPS	I	ST	
IC4	PPS	PPS	PPS	PPS	I	ST	
IC5	PPS	PPS	PPS	PPS	I	ST	

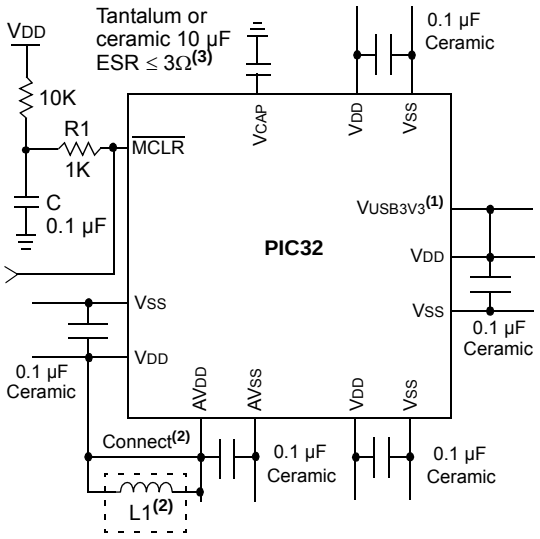
Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer; PPS = Peripheral Pin Select; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

2: Pin number for PIC32MX1XX devices only.

3: Pin number for PIC32MX2XX devices only.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: If the USB module is not used, this pin must be connected to VDD.

2: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 3Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{FCNV}{2}$$ (i.e., ADC conversion rate/2)

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

1: Aluminum or electrolytic capacitors should not be used. ESR ≤ 3Ω from -40ºC to 125ºC @ SYSCLK frequency (i.e., MIPS).

2.2.1 BULK CAPACITORS

The use of a bulk capacitor is recommended to improve power supply stability. Typical values range from 4.7 µF to 47 µF. This capacitor should be located as close to the device as possible.

2.3 Capacitor on Internal Voltage Regulator (VCAP)

2.3.1 INTERNAL REGULATOR MODE

A low-ESR (3 ohm) capacitor is required on the VCAP pin, which is used to stabilize the internal voltage regulator output. The VCAP pin must not be connected to VDD, and must have a CEFC capacitor, with at least a 6V rating, connected to ground. The type can be ceramic or tantalum. Refer to **30.0 "Electrical Characteristics"** for additional information on CEFC specifications.

2.4 Master Clear (MCLR) Pin

The MCLR pin provides two specific device functions:

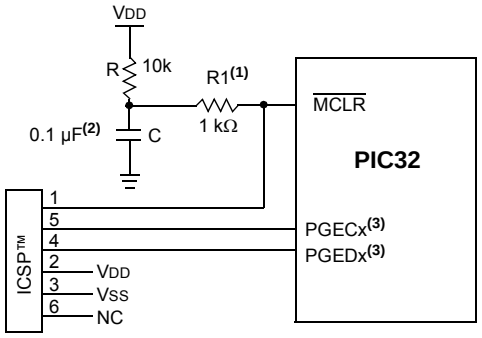
- Device Reset
- Device programming and debugging

Pulling The MCLR pin low generates a device Reset. Figure 2-2 illustrates a typical MCLR circuit. During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as illustrated in Figure 2-2, it is recommended that the capacitor C, be isolated from the MCLR pin during programming and debugging operations.

Place the components illustrated in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



Note 1: 470Ω ≤ R1 ≤ 1Ω will limit any current flowing into MCLR from the external capacitor C, in the event of MCLR pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met without interfering with the Debug/Programmer tools.

2: The capacitor can be sized to prevent unintentional Resets from brief glitches or to extend the device Reset period during POR.

3: No pull-ups or bypass capacitors are allowed on active debug/program PGECx/PGEDx pins.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

2.8.1 CRYSTAL OSCILLATOR DESIGN CONSIDERATION

The following example assumptions are used to calculate the Primary Oscillator loading capacitor values:

- CIN = PIC32_OSC2_Pin Capacitance = ~4-5 pF
- COUT = PIC32_OSC1_Pin Capacitance = ~4-5 pF
- C1 and C2 = XTAL manufacturing recommended loading capacitance
- Estimated PCB stray capacitance, (i.e.,12 mm length) = 2.5 pF

EXAMPLE 2-1: CRYSTAL LOAD CAPACITOR CALCULATION

Crystal manufacturer recommended: $C1 = C2 = 15\ pF$

Therefore:

$$C_{LOAD} = \{([C_{IN} + C1] * [C_{OUT} + C2]) / [C_{IN} + C1 + C2 + C_{OUT}] \} + \text{estimated oscillator PCB stray capacitance}$$
$$= \{([5 + 15][5 + 15]) / [5 + 15 + 15 + 5] \} + 2.5\ pF$$
$$= \{([20][20]) / [40] \} + 2.5$$
$$= 10 + 2.5 = 12.5\ pF$$

Rounded to the nearest standard value or 12 pF in this example for Primary Oscillator crystals "C1" and "C2".

The following tips are used to increase oscillator gain, (i.e., to increase peak-to-peak oscillator signal):

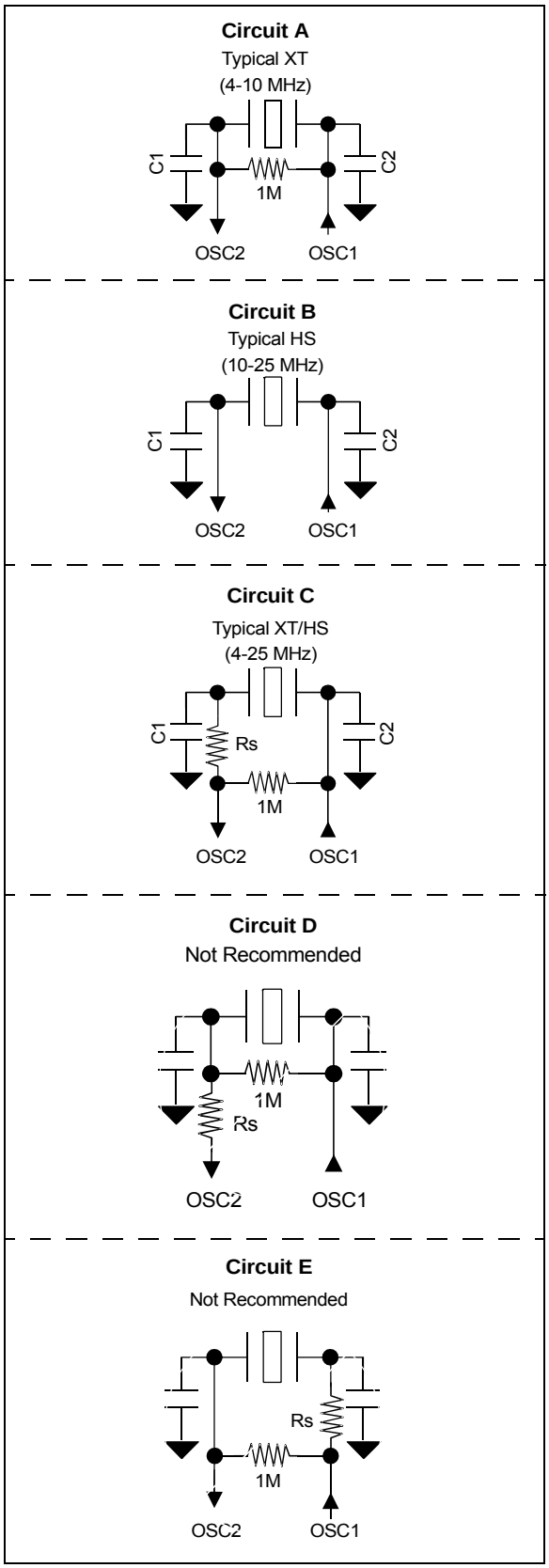
- Select a crystal with a lower "minimum" power drive rating
- Select an crystal oscillator with a lower XTAL manufacturing "ESR" rating.
- Add a parallel resistor across the crystal. The smaller the resistor value the greater the gain. It is recommended to stay in the range of 600k to 1M
- C1 and C2 values also affect the gain of the oscillator. The lower the values, the higher the gain.
- C2/C1 ratio also affects gain. To increase the gain, make C1 slightly smaller than C2, which will also help start-up performance.

Note: Do not add excessive gain such that the oscillator signal is clipped, flat on top of the sine wave. If so, you need to reduce the gain or add a series resistor, RS, as shown in circuit "C" in Figure 2-4. Failure to do so will stress and age the crystal, which can result in an early failure. Adjust the gain to trim the max peak-to-peak to ~VDD-0.6V. When measuring the oscillator signal you must use a FET scope probe or a probe with ≤ 1.5 pF or the scope probe itself will unduly change the gain and peak-to-peak levels.

2.8.1.1 Additional Microchip References

- AN588 *"PICmicro® Microcontroller Oscillator Design Guide"*
- AN826 *"Crystal Oscillator Basics and Crystal Selection for rfPIC™ and PICmicro® Devices"*
- AN849 *"Basic PICmicro® Oscillator Design"*

FIGURE 2-4: PRIMARY CRYSTAL OSCILLATOR CIRCUIT RECOMMENDATIONS



REGISTER 4-7: BMXPFMSZ: PROGRAM FLASH (PFM) SIZE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R	R	R	R	R	R	R	R
	BMXPFMSZ<31:24>							
23:16	R	R	R	R	R	R	R	R
	BMXPFMSZ<23:16>							
15:8	R	R	R	R	R	R	R	R
	BMXPFMSZ<15:8>							
7:0	R	R	R	R	R	R	R	R
	BMXPFMSZ<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **BMXPFMSZ<31:0>:** Program Flash Memory (PFM) Size bits
Static value that indicates the size of the PFM in bytes:
0x00004000 = Device has 16 KB Flash
0x00008000 = Device has 32 KB Flash
0x00010000 = Device has 64 KB Flash
0x00020000 = Device has 128 KB Flash
0x00040000 = Device has 256 KB Flash

REGISTER 4-8: BMXBOOTSZ: BOOT FLASH (IFM) SIZE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R	R	R	R	R	R	R	R
	BMXBOOTSZ<31:24>							
23:16	R	R	R	R	R	R	R	R
	BMXBOOTSZ<23:16>							
15:8	R	R	R	R	R	R	R	R
	BMXBOOTSZ<15:8>							
7:0	R	R	R	R	R	R	R	R
	BMXBOOTSZ<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **BMXBOOTSZ<31:0>:** Boot Flash Memory (BFM) Size bits
Static value that indicates the size of the Boot PFM in bytes:
0x00000C00 = Device has 3 KB boot Flash

REGISTER 5-1: NVMCON: PROGRAMMING CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R-0	R-0	R-0	U-0	U-0	U-0
	WR	WREN	WRERR(1)	LVDERR(1)	LVDSTAT(1)	—	—	—
7:0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	—	NVMOP<3:0>			

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **WR:** Write Control bit

This bit is writable when WREN = 1 and the unlock sequence is followed.

1 = Initiate a Flash operation. Hardware clears this bit when the operation completes
0 = Flash operation is complete or inactive

bit 14 **WREN:** Write Enable bit

This is the only bit in this register reset by a device Reset.

1 = Enable writes to WR bit and enables LVD circuit
0 = Disable writes to WR bit and disables LVD circuit

bit 13 **WRERR:** Write Error bit(1)

This bit is read-only and is automatically set by hardware.

1 = Program or erase sequence did not complete successfully
0 = Program or erase sequence completed normally

bit 12 **LVDERR:** Low-Voltage Detect Error bit (LVD circuit must be enabled)(1)

This bit is read-only and is automatically set by hardware.

1 = Low-voltage detected (possible data corruption, if WRERR is set)
0 = Voltage level is acceptable for programming

bit 11 **LVDSTAT:** Low-Voltage Detect Status bit (LVD circuit must be enabled)(1)

This bit is read-only and is automatically set and cleared by the hardware.

1 = Low-voltage event is active
0 = Low-voltage event is not active

bit 10-4 **Unimplemented:** Read as '0'

bit 3-0 **NVMOP<3:0>:** NVM Operation bits

These bits are writable when WREN = 0.

1111 = Reserved
•
•
•
0111 = Reserved
0110 = No operation
0101 = Program Flash Memory (PFM) erase operation: erases PFM, if all pages are not write-protected
0100 = Page erase operation: erases page selected by NVMADDR, if it is not write-protected
0011 = Row program operation: programs row selected by NVMADDR, if it is not write-protected
0010 = No operation
0001 = Word program operation: programs word selected by NVMADDR, if it is not write-protected
0000 = No operation

Note 1: This bit is cleared by setting NVMOP == 'b0000, and initiating a Flash operation (i.e., WR).

6.1 Reset Control Registers

TABLE 6-1: RESET CONTROL REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
F600	RCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	CMR	VREGS	EXTR	SWR	—	WDTO	SLEEP	IDLE	BOR	POR	xxxx(2)
F610	RSWRST	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SWRST	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

2: Reset values are dependent on the DEVCFGx Configuration bits and the type of reset.

REGISTER 8-3: REFOCON: REFERENCE OSCILLATOR CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	RODIV<14:8>(1,3)						
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	RODIV<7:0>(1,3)							
15:8	R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0, HC	R-0, HS, HC
	ON	—	SIDL	OE	RSLP(2)	—	DIVSWEN	ACTIVE
7:0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	—	ROSEL<3:0>(1)			

Legend:	HC = Hardware Clearable	HS = Hardware Settable	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **Unimplemented:** Read as '0'

bit 30-16 **RODIV<14:0>** Reference Clock Divider bits(1,3)

The value selects the reference clock divider bits. See Figure 8-1 for information.

bit 15 **ON:** Output Enable bit

1 = Reference Oscillator module is enabled
0 = Reference Oscillator module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Peripheral Stop in Idle Mode bit

1 = Discontinue module operation when the device enters Idle mode
0 = Continue module operation when the device enters Idle mode

bit 12 **OE:** Reference Clock Output Enable bit

1 = Reference clock is driven out on REFCLKO pin
0 = Reference clock is not driven out on REFCLKO pin

bit 11 **RSLP:** Reference Oscillator Module Run in Sleep bit(2)

1 = Reference Oscillator module output continues to run in Sleep
0 = Reference Oscillator module output is disabled in Sleep

bit 10 **Unimplemented:** Read as '0'

bit 9 **DIVSWEN:** Divider Switch Enable bit

1 = Divider switch is in progress
0 = Divider switch is complete

bit 8 **ACTIVE:** Reference Clock Request Status bit

1 = Reference clock request is active
0 = Reference clock request is not active

bit 7-4 **Unimplemented:** Read as '0'

Note 1: The ROSEL and RODIV bits should not be written while the ACTIVE bit is '1', as undefined behavior may result.

2: This bit is ignored when the ROSEL<3:0> bits = 0000 or 0001.

3: While the ON bit is set to '1', writes to these bits do not take effect until the DIVSWEN bit is also set to '1'.

REGISTER 9-4: DCRCCON: DMA CRC CONTROL REGISTER (CONTINUED)

bit 6 **CRCAPP:** CRC Append Mode bit(1)
- 1 = The DMA transfers data from the source into the CRC but NOT to the destination. When a block transfer completes the DMA writes the calculated CRC value to the location given by CHxDSA
- 0 = The DMA transfers data from the source through the CRC obeying WBO as it writes the data to the destination

bit 5 **CRCTYP:** CRC Type Selection bit
- 1 = The CRC module will calculate an IP header checksum
- 0 = The CRC module will calculate a LFSR CRC

bit 4-3 **Unimplemented:** Read as '0'

bit 2-0 **CRCCH<2:0>:** CRC Channel Select bits
- 111 = CRC is assigned to Channel 7
- 110 = CRC is assigned to Channel 6
- 101 = CRC is assigned to Channel 5
- 100 = CRC is assigned to Channel 4
- 011 = CRC is assigned to Channel 3
- 010 = CRC is assigned to Channel 2
- 001 = CRC is assigned to Channel 1
- 000 = CRC is assigned to Channel 0

Note 1: When WBO = 1, unaligned transfers are not supported and the CRCAPP bit cannot be set.

10.1 USB Control Registers

TABLE 10-1: USB REGISTER MAP

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
5040	U1OTGIR(2)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	IDIF	T1MSECIF	LSTATEIF	ACTVIF	SESVDIF	SESENDIF	—	VBUSVDIF	0000
5050	U1OTGIE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	IDIE	T1MSECIE	LSTATEIE	ACTVIE	SESVDIE	SESENDIE	—	VBUSVDIE	0000
5060	U1OTGSTAT(3)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	ID	—	LSTATE	—	SESVD	SESEND	—	VBUSVD	0000
5070	U1OTGCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	DPPULUP	DMPULUP	DPPULDWN	DMPULDWN	VBUSON	OTGEN	VBUSCHG	VBUSDIS	0000
5080	U1PWRC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	UACTPND(4)	—	—	USLPGRD	USBBUSY	—	USUSPEND	USBPWR	0000
5200	U1IR(2)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	STALLIF	ATTACHIF	RESUMEIF	IDLEIF	TRNIF	SOFIF	UERRIF	URSTIF	0000
																		DETACHIF	0000
5210	U1IE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	STALLIE	ATTACHIE	RESUMEIE	IDLEIE	TRNIE	SOFIE	UERRIE	URSTIE	0000
																		DETACHIE	0000
5220	U1EIR(2)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	BTSEF	BMXEF	DMAEF	BTOEF	DFN8EF	CRC16EF	CRC5EF	PIDEF	0000
																	EOFEF		0000
5230	U1EIE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	BTSEE	BMXEE	DMAEE	BTOEE	DFN8EE	CRC16EE	CRC5EE	PIDEE	0000
																	EOFEE		0000
5240	U1STAT(3)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	ENDPT<3:0>				DIR	PPBI	—	—	0000
5250	U1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	JSTATE	SE0	PKTDIS	USBRST	HOSTEN	RESUME	PPBRST	USBEN	0000
													TOKBUSY					SOFEN	0000
5260	U1ADDR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	LSPDEN	DEVADDR<6:0>							0000
5270	U1BDTP1	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	BDTPTRL<15:9>							—	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: With the exception of those noted, all registers in this table (except as noted) have corresponding CLR, SET and INV registers at their virtual address, plus an offset of 0x4, 0x8, and 0xC respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

2: This register does not have associated SET and INV registers.

3: This register does not have associated CLR, SET and INV registers.

4: Reset value for this bit is undefined.

REGISTER 10-3: U1OTGSTAT: USB OTG STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R-0	U-0	R-0	U-0	R-0	R-0	U-0	R-0
	ID	—	LSTATE	—	SESVD	SESEND	—	VBUSVD

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **ID:** ID Pin State Indicator bit
- 1 = No cable is attached or a "type B" cable has been inserted into the USB receptacle
- 0 = A "type A" OTG cable has been inserted into the USB receptacle

bit 6 **Unimplemented:** Read as '0'

bit 5 **LSTATE:** Line State Stable Indicator bit
- 1 = USB line state (SE0 (U1CON<6>) bit and JSTATE (U1CON<7>)) bit has been stable for previous 1 ms
- 0 = USB line state (SE0 and JSTATE) has not been stable for previous 1 ms

bit 4 **Unimplemented:** Read as '0'

bit 3 **SESVD:** Session Valid Indicator bit
- 1 = VBUS voltage is above Session Valid on the A or B device
- 0 = VBUS voltage is below Session Valid on the A or B device

bit 2 **SESEND:** B-Device Session End Indicator bit
- 1 = VBUS voltage is below Session Valid on the B device
- 0 = VBUS voltage is above Session Valid on the B device

bit 1 **Unimplemented:** Read as '0'

bit 0 **VBUSVD:** A-Device VBUS Valid Indicator bit
- 1 = VBUS voltage is above Session Valid on the A device
- 0 = VBUS voltage is below Session Valid on the A device

TABLE 11-1: INPUT PIN SELECTION

Peripheral Pin	[*pin name*]R SFR	[*pin name*]R bits	[*pin name*]R Value to RPn Pin Selection
INT4	INT4R	INT4R<3:0>	0000 = RPA0 0001 = RPB3 0010 = RPB4 0011 = RPB15 0100 = RPB7 0101 = RPC7(2) 0110 = RPC0(1) 0111 = RPC5(2) 1000 = Reserved • • • 1111 = Reserved
T2CK	T2CKR	T2CKR<3:0>	
IC4	IC4R	IC4R<3:0>	
$\overline{SS1}$	SS1R	SS1R<3:0>	
REFCLKI	REFCLKIR	REFCLKIR<3:0>	
INT3	INT3R	INT3R<3:0>	0000 = RPA1 0001 = RPB5 0010 = RPB1 0011 = RPB11 0100 = RPB8 0101 = RPA8(2) 0110 = RPC8(2) 0111 = RPA9(2) 1000 = Reserved • • • 1111 = Reserved
T3CK	T3CKR	T3CKR<3:0>	
IC3	IC3R	IC3R<3:0>	
$\overline{U1CTS}$	U1CTSR	U1CTSR<3:0>	
U2RX	U2RXR	U2RXR<3:0>	
SDI1	SDI1R	SDI1R<3:0>	
INT2	INT2R	INT2R<3:0>	0000 = RPA2 0001 = RPB6 0010 = RPA4 0011 = RPB13 0100 = RPB2 0101 = RPC6(2) 0110 = RPC1(1) 0111 = RPC3(1) 1000 = Reserved • • • 1111 = Reserved
T4CK	T4CKR	T4CKR<3:0>	
IC1	IC1R	IC1R<3:0>	
IC5	IC5R	IC5R<3:0>	
U1RX	U1RXR	U1RXR<3:0>	
$\overline{U2CTS}$	U2CTSR	U2CTSR<3:0>	
SDI2	SDI2R	SDI2R<3:0>	
OCFB	OCFBR	OCFBR<3:0>	
INT1	INT1R	INT1R<3:0>	0000 = RPA3 0001 = RPB14 0010 = RPB0 0011 = RPB10 0100 = RPB9 0101 = RPC9(1) 0110 = RPC2(2) 0111 = RPC4(2) 1000 = Reserved • • • 1111 = Reserved
T5CK	T5CKR	T5CKR<3:0>	
IC2	IC2R	IC2R<3:0>	
$\overline{SS2}$	SS2R	SS2R<3:0>	
OCFA	OCFAR	OCFAR<3:0>	

Note 1: This pin is not available on 28-pin devices.

2: This pin is only available on 44-pin devices.

15.1 Input Capture Control Registers

TABLE 15-1: INPUT CAPTURE 1-INPUT CAPTURE 5 REGISTER MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
2000	IC1CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2010	IC1BUF	31:16	IC1BUF<31:0>																xxxx
		15:0																	xxxx
2200	IC2CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2210	IC2BUF	31:16	IC2BUF<31:0>																xxxx
		15:0																	xxxx
2400	IC3CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2410	IC3BUF	31:16	IC3BUF<31:0>																xxxx
		15:0																	xxxx
2600	IC4CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2610	IC4BUF	31:16	IC4BUF<31:0>																xxxx
		15:0																	xxxx
2800	IC5CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2810	IC5BUF	31:16	IC5BUF<31:0>																xxxx
		15:0																	xxxx

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

TABLE 26-2: PERIPHERAL MODULE DISABLE REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
F240	PMD1	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	CVRMD	—	—	—	CTMUMD	—	—	—	—	—	—	—	AD1MD	0000
F250	PMD2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	CMP3MD	CMP2MD	CMP1MD	0000
F260	PMD3	31:16	—	—	—	—	—	—	—	—	—	—	—	OC5MD	OC4MD	OC3MD	OC2MD	OC1MD	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	IC5MD	IC4MD	IC3MD	IC2MD	IC1MD	0000
F270	PMD4	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	T5MD	T4MD	T3MD	T2MD	T1MD	0000
F280	PMD5	31:16	—	—	—	—	—	—	—	USB1MD	—	—	—	—	—	—	I2C1MD	I2C1MD	0000
		15:0	—	—	—	—	—	—	SPI2MD	SPI1MD	—	—	—	—	—	—	U2MD	U1MD	0000
F290	PMD6	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	PMPMD	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	REFOMD	RTCCMD	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

27.0 SPECIAL FEATURES

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 32. "Configuration"** (DS60001124) and **Section 33. "Programming and Diagnostics"** (DS60001129), which are available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

PIC32MX1XX/2XX 28/36/44-pin Family devices include the following features intended to maximize application flexibility, reliability and minimize cost through elimination of external components.

- Flexible device configuration
- Joint Test Action Group (JTAG) interface
- In-Circuit Serial Programming™ (ICSP™)

27.1 Configuration Bits

The Configuration bits can be programmed using the following registers to select various device configurations.

- DEVCFG0: Device Configuration Word 0
- DEVCFG1: Device Configuration Word 1
- DEVCFG2: Device Configuration Word 2
- DEVCFG3: Device Configuration Word 3
- CFGCON: Configuration Control Register

In addition, the DEVID register (Register 27-6) provides device and revision information.

29.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers (MCU) and dsPIC® digital signal controllers (DSC) are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® X IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB XC Compiler
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB X SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers/Programmers
  - MPLAB ICD 3
  - PICkit™ 3
- Device Programmers
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits and Starter Kits
- Third-party development tools

29.1 MPLAB X Integrated Development Environment Software

The MPLAB X IDE is a single, unified graphical user interface for Microchip and third-party software, and hardware development tool that runs on Windows®, Linux and Mac OS® X. Based on the NetBeans IDE, MPLAB X IDE is an entirely new IDE with a host of free software components and plug-ins for high-performance application development and debugging. Moving between tools and upgrading from software simulators to hardware debugging and programming tools is simple with the seamless user interface.

With complete project management, visual call graphs, a configurable watch window and a feature-rich editor that includes code completion and context menus, MPLAB X IDE is flexible and friendly enough for new users. With the ability to support multiple tools on multiple projects with simultaneous debugging, MPLAB X IDE is also suitable for the needs of experienced users.

Feature-Rich Editor:

- Color syntax highlighting
- Smart code completion makes suggestions and provides hints as you type
- Automatic code formatting based on user-defined rules
- Live parsing

User-Friendly, Customizable Interface:

- Fully customizable interface: toolbars, toolbar buttons, windows, window placement, etc.
- Call graph window

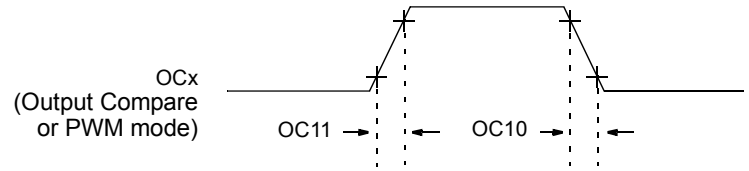
Project-Based Workspaces:

- Multiple projects
- Multiple tools
- Multiple configurations
- Simultaneous debugging sessions

File History and Bug Tracking:

- Local file history feature
- Built-in support for Bugzilla issue tracker

FIGURE 30-8: OUTPUT COMPARE MODULE (OCx) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

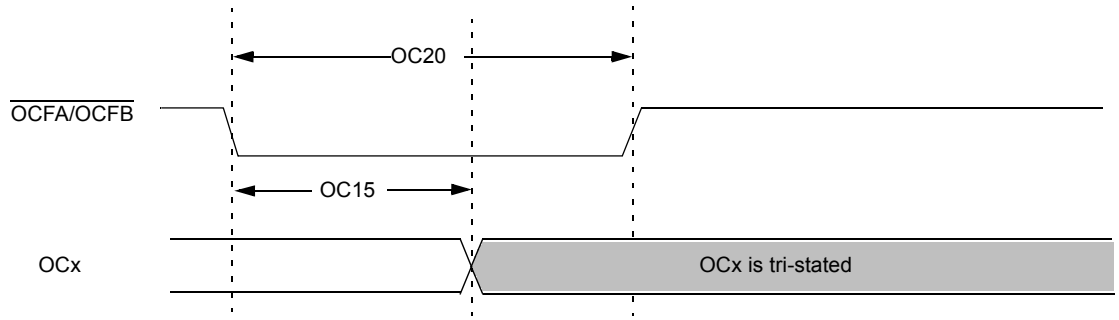
TABLE 30-26: OUTPUT COMPARE MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See parameter DO32
OC11	TccR	OCx Output Rise Time	—	—	—	ns	See parameter DO31

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 30-9: OCx/PWM MODULE TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-27: SIMPLE OCx/PWM MODE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param No.	**Symbol**	**Characteristics(1)**	**Min**	**Typical(2)**	**Max**	**Units**	**Conditions**
OC15	TFD	Fault Input to PWM I/O Change	—	—	50	ns	—
OC20	TFLT	Fault Input Pulse Width	50	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 31-8: SPIx MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
MSP70	TscL	SCKx Input Low Time **(Note 1,2)**	Tsck/2	—	—	ns	—
MSP71	TscH	SCKx Input High Time **(Note 1,2)**	Tsck/2	—	—	ns	—
MSP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance **(Note 2)**	5	—	25	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: The minimum clock period for SCKx is 40 ns.

TABLE 31-9: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS

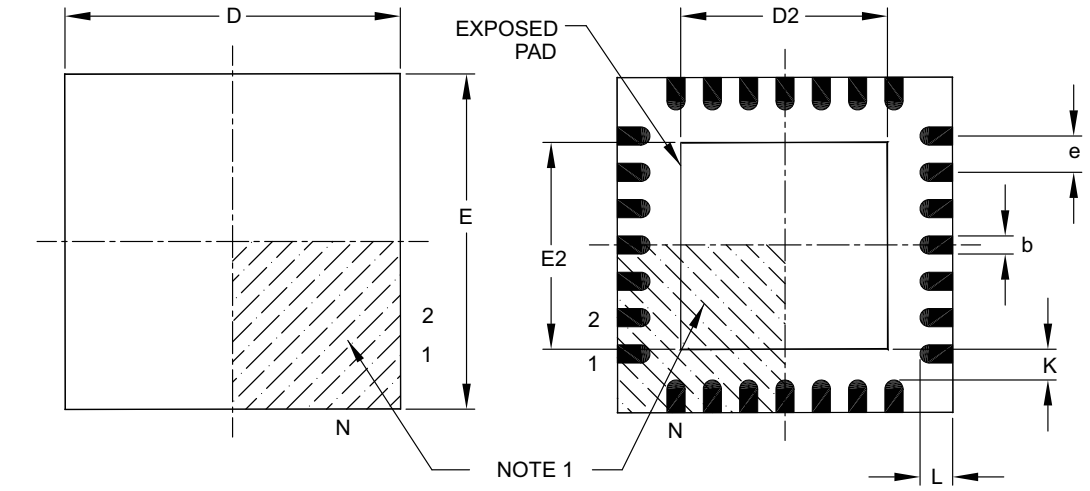
AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
SP70	TscL	SCKx Input Low Time **(Note 1,2)**	Tsck/2	—	—	ns	—
SP71	TscH	SCKx Input High Time **(Note 1,2)**	Tsck/2	—	—	ns	—

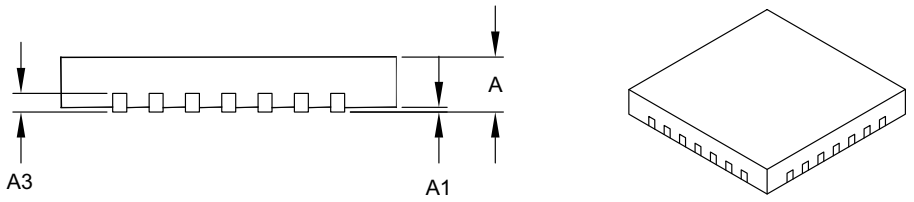
Note 1: These parameters are characterized, but not tested in manufacturing.

2: The minimum clock period for SCKx is 40 ns.

28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	3.65	3.70	4.20
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	3.65	3.70	4.20
Contact Width	b	0.23	0.30	0.35
Contact Length	L	0.50	0.55	0.70
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

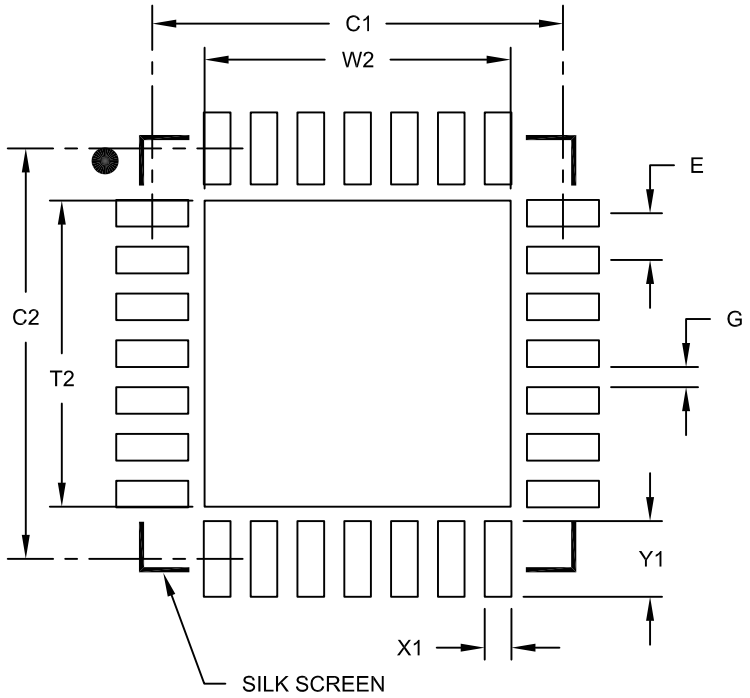
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-105B

28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			4.25
Optional Center Pad Length	T2			4.25
Contact Pad Spacing	C1		5.70	
Contact Pad Spacing	C2		5.70	
Contact Pad Width (X28)	X1			0.37
Contact Pad Length (X28)	Y1			1.00
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2105A